

Figure 1

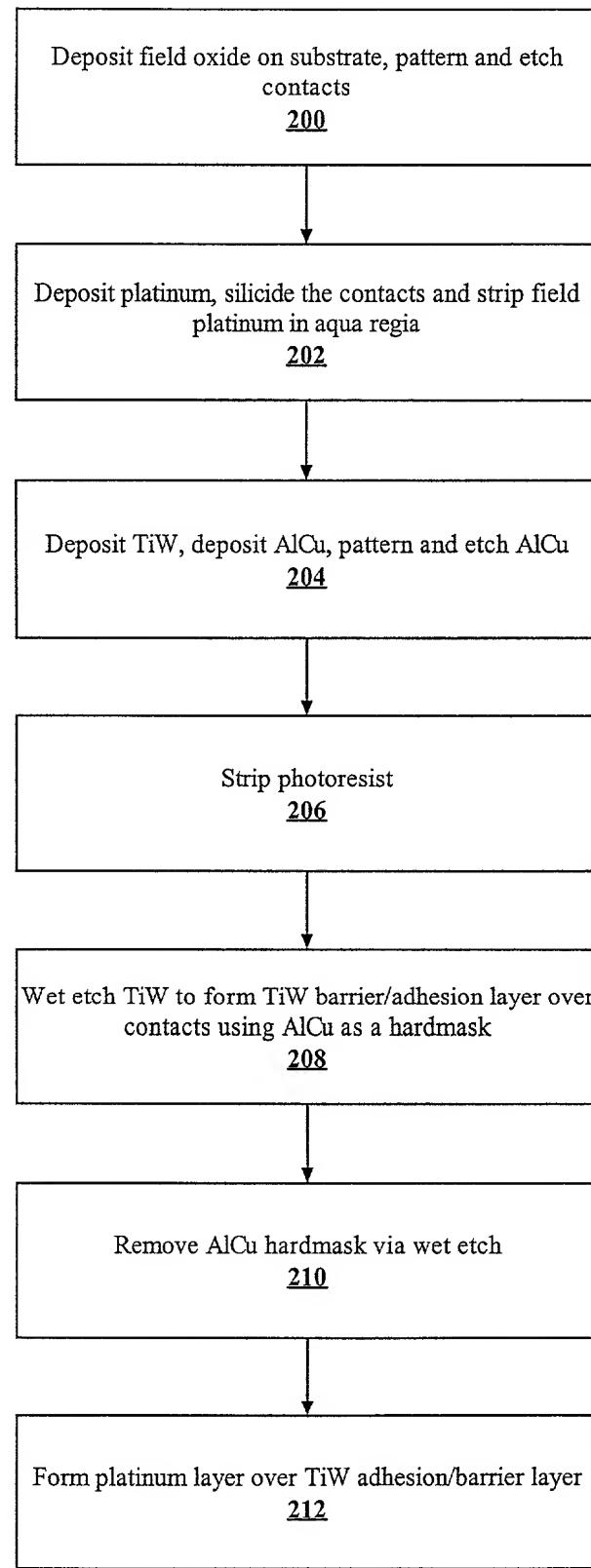


Figure 2

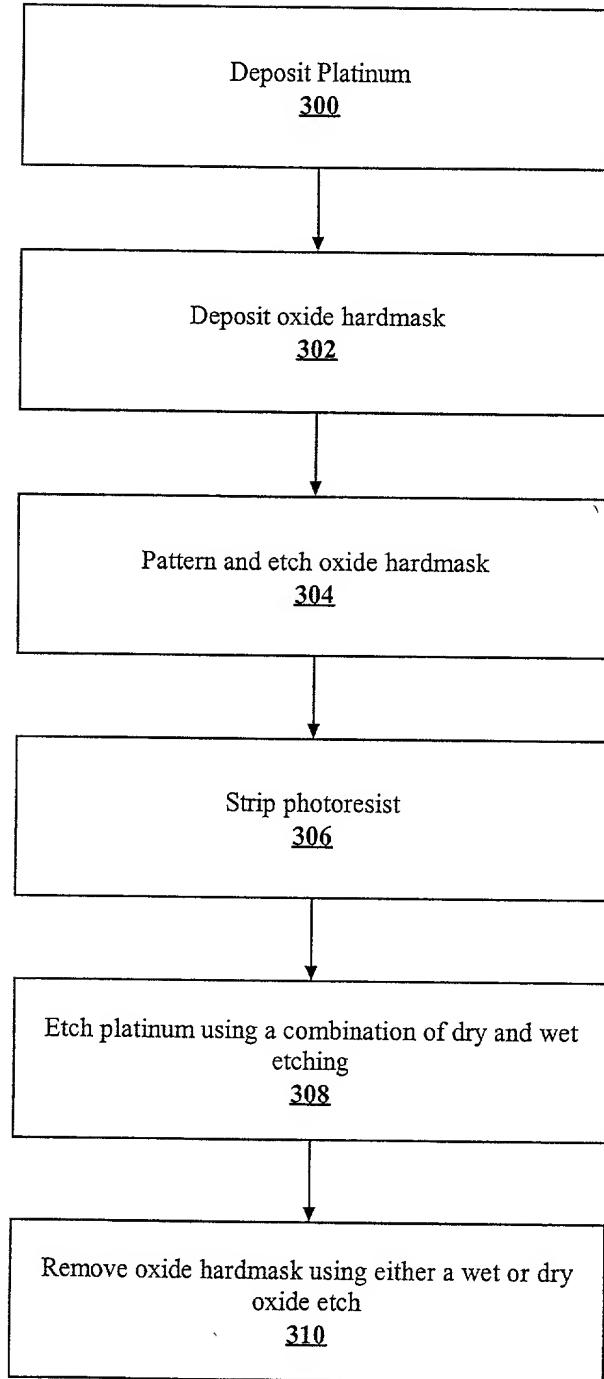


Figure 3

- (1)
- Pattern and etch contacts
 - Strip resist
 - Deposit Platinum and silicide the contacts
 - Strip field Pt in aqua regia

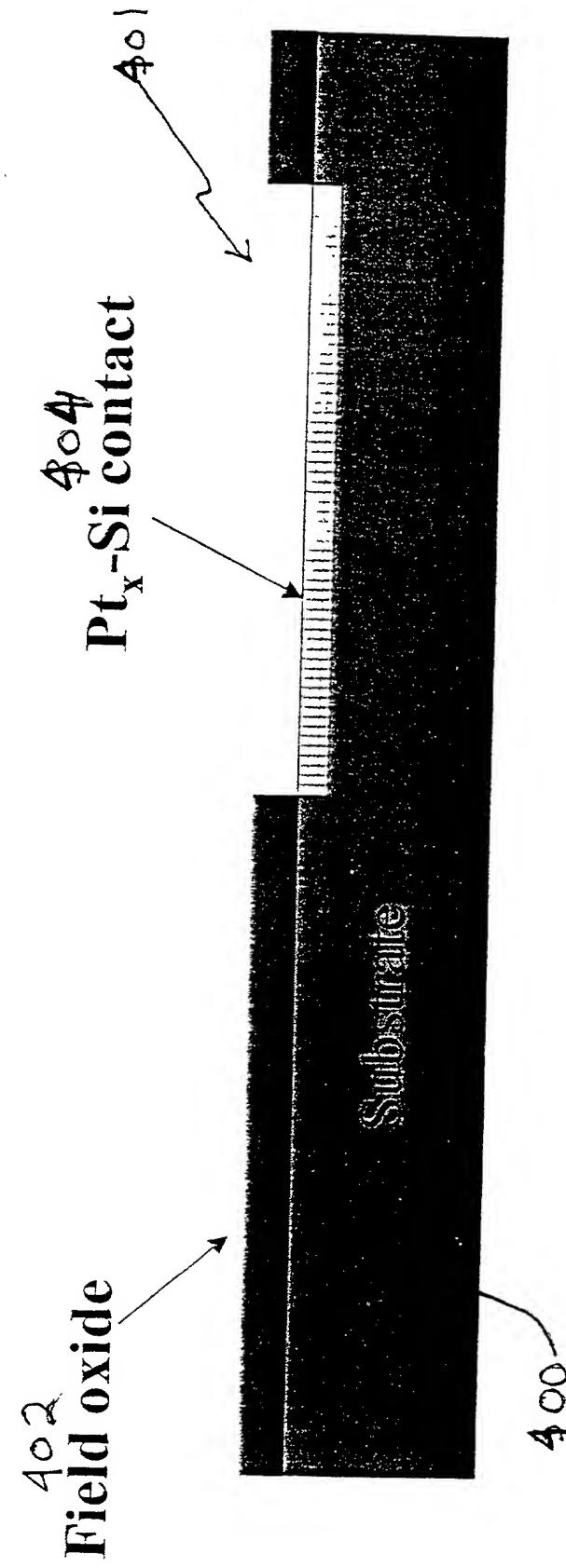


Figure 4a

(2)
Deposit TiW

Pattern and etch TiW barrier over contacts
Strip resist

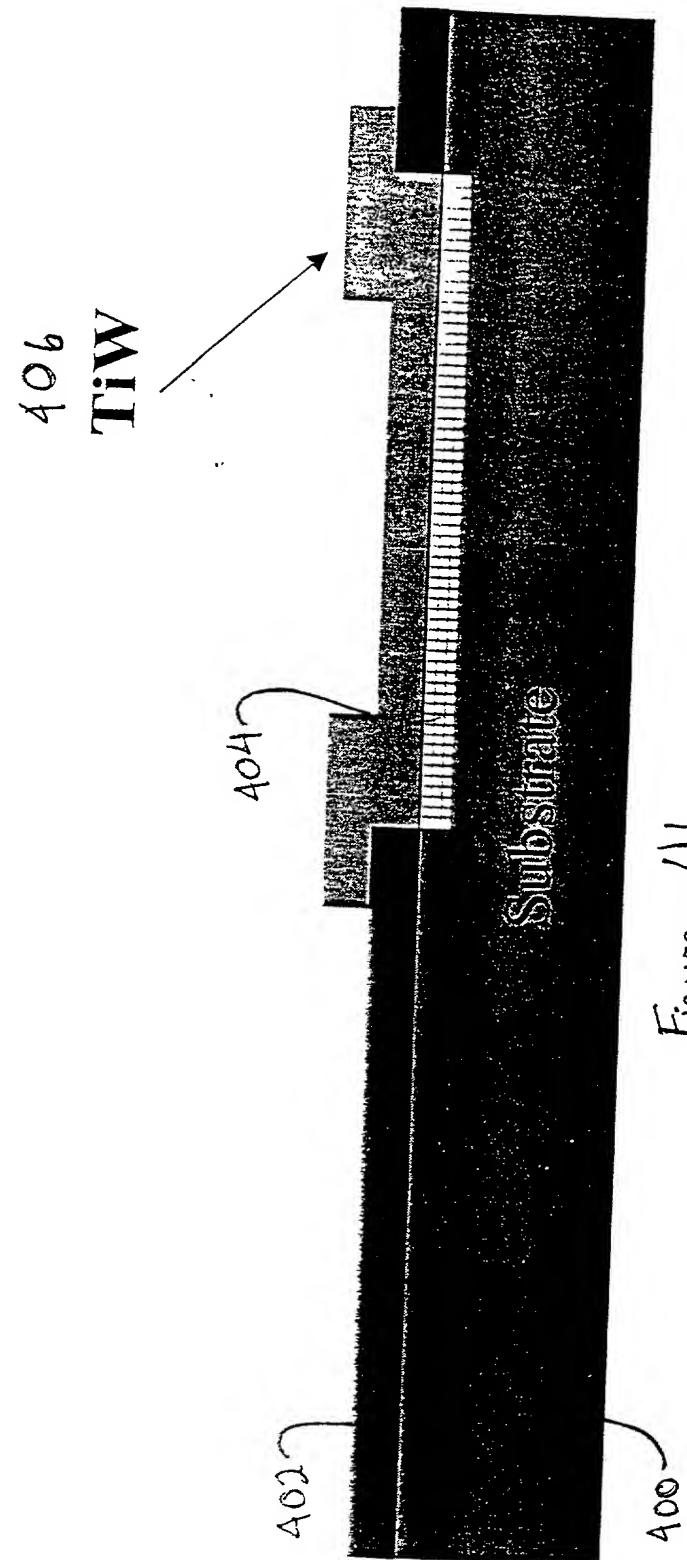


Figure 4b

Note: contingency field on reticle for TiW adhesion layer under all interconnect

(3)

Deposit Platinum for interconnect

Deposit oxide for hardmask

Pattern and etch hardmask

Strip resist

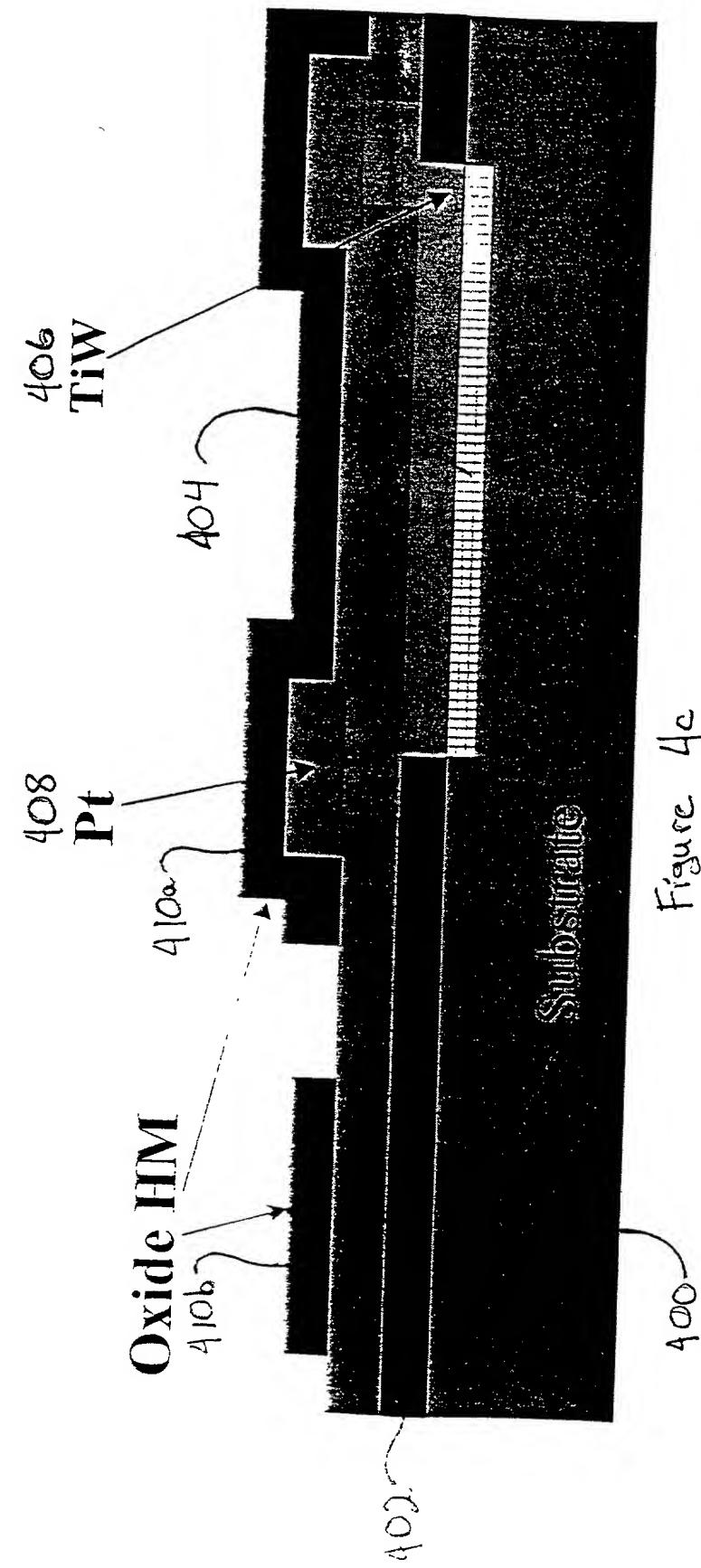


Figure 4c

Etch Platinum for interconnect
Remove hardmask

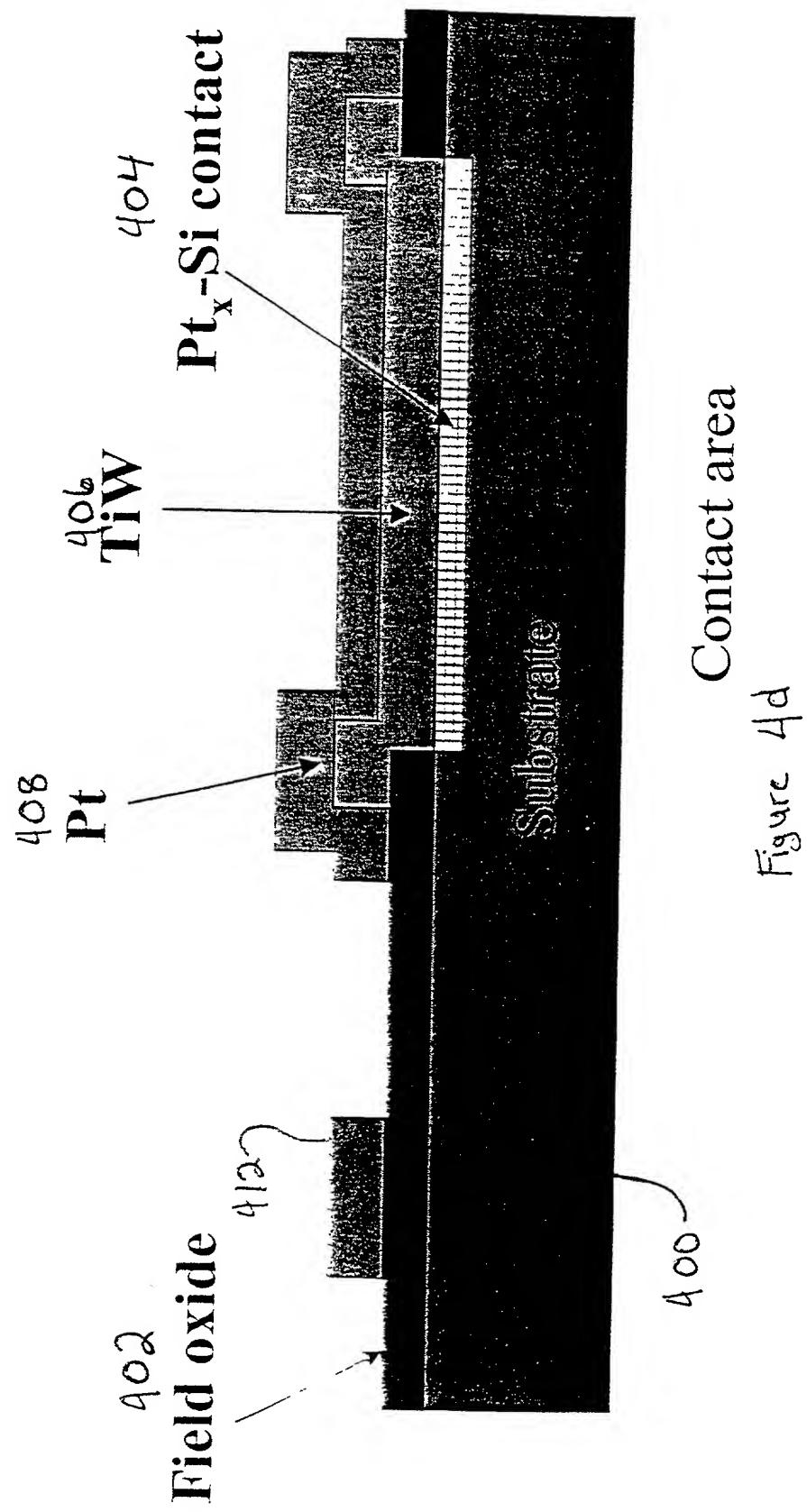


Figure 4d

Contact area

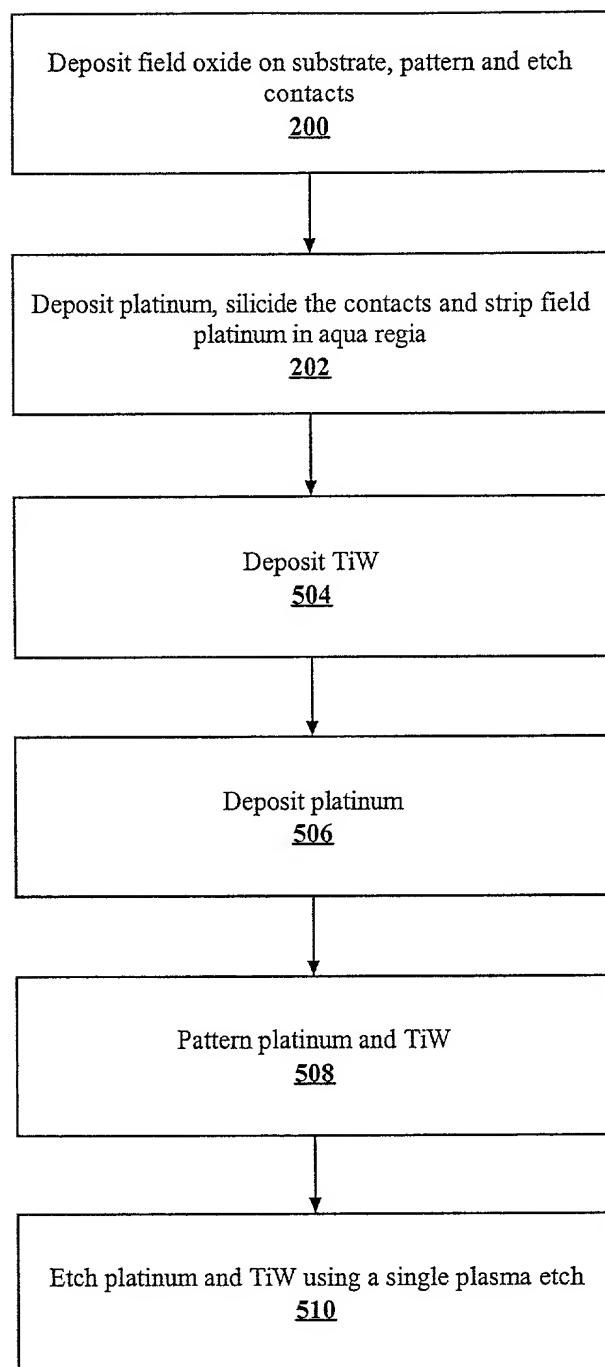


Figure 5

Figure 6

